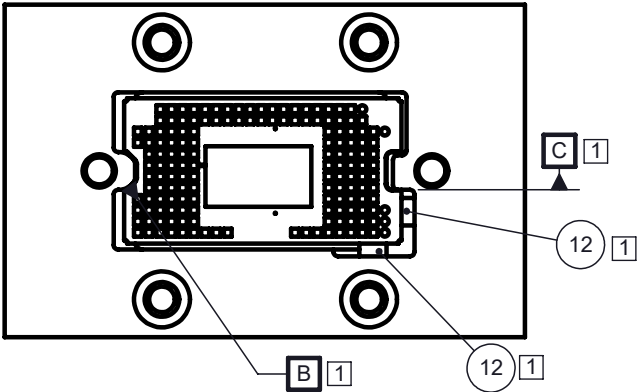
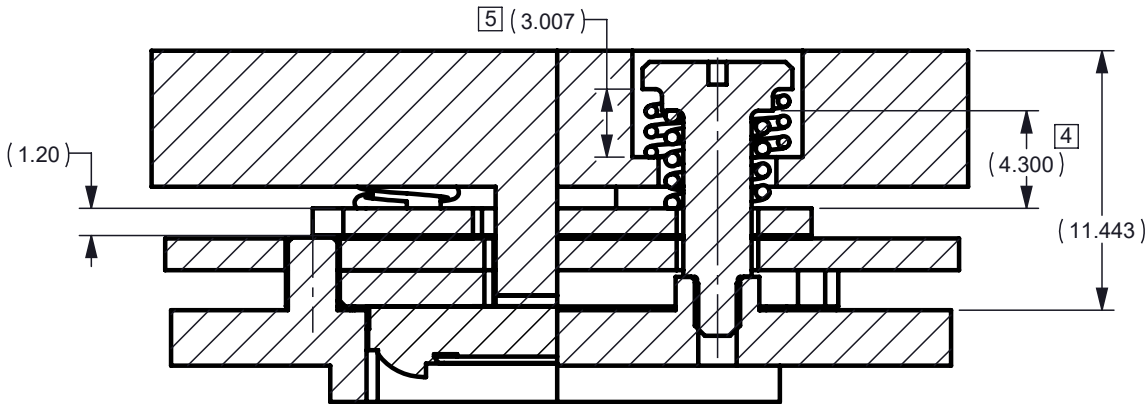
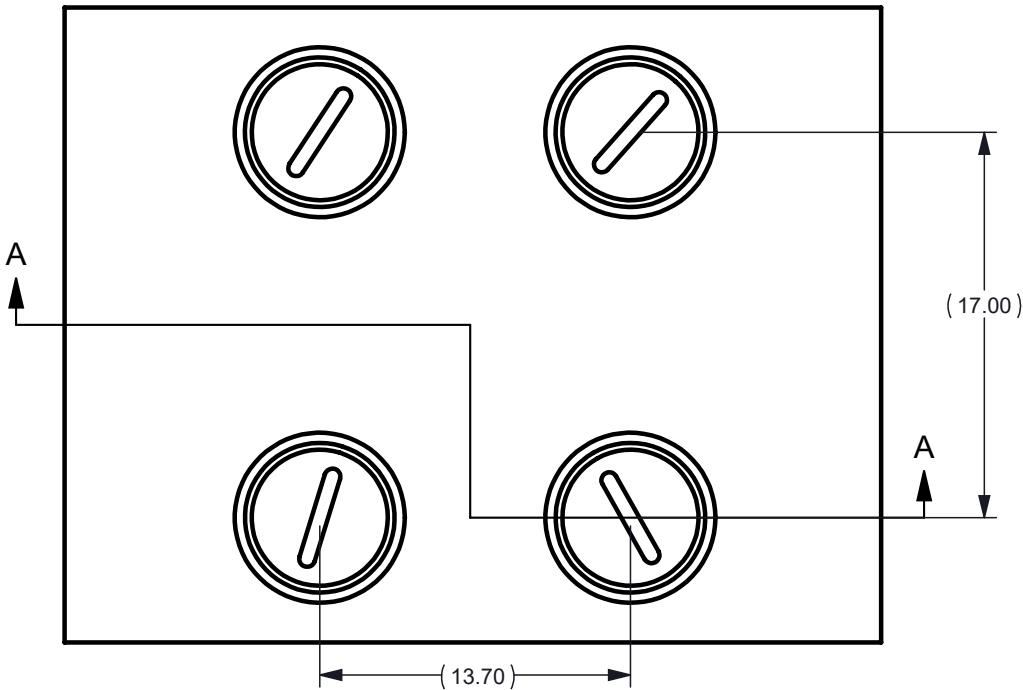


NOTES: UNLESS OTHERWISE SPECIFIED:

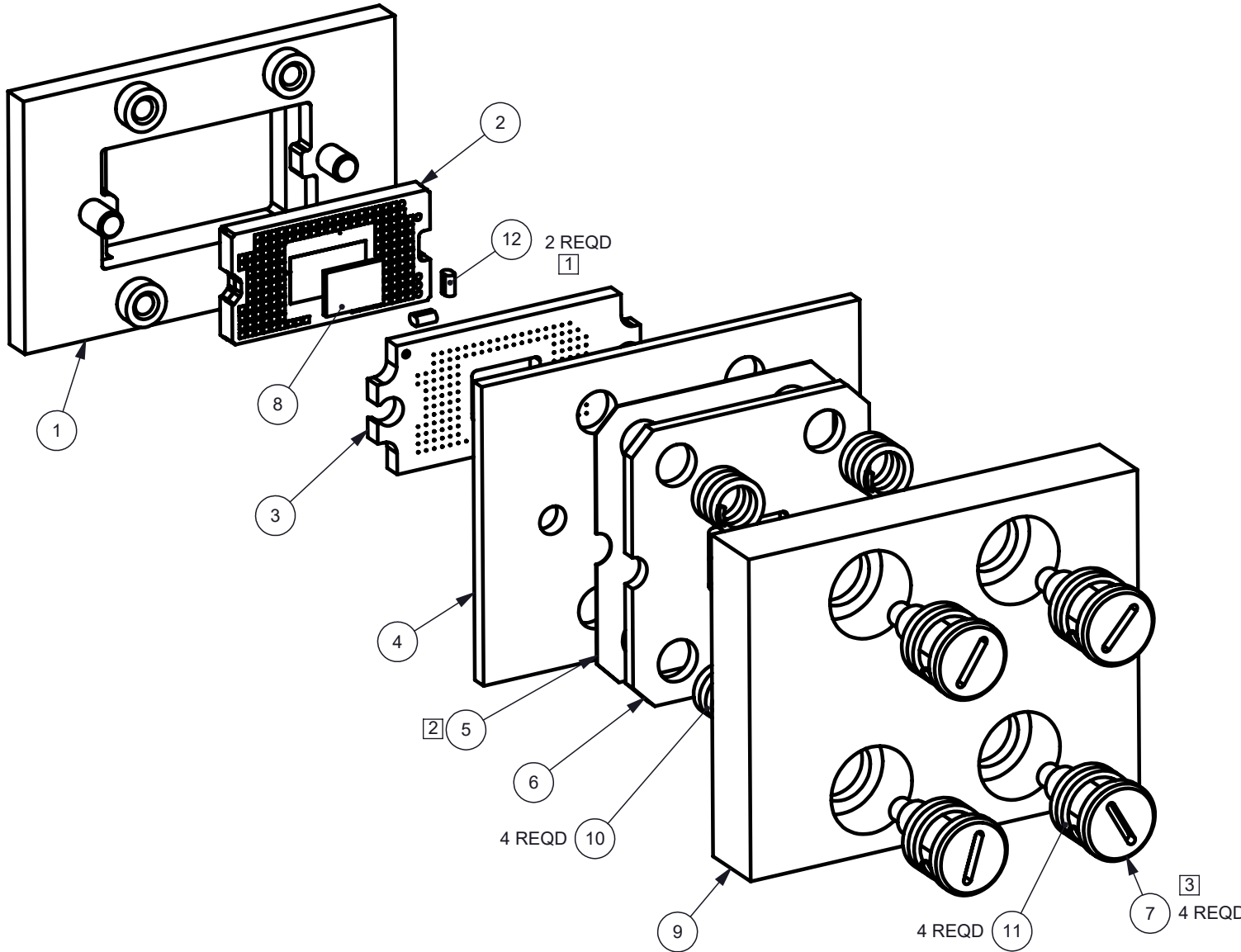
- [1] THE DMD (ITEM 2) SHOULD BE ALIGNED TO DATUMS 'B' AND 'C' AS SHOWN IN VIEW A. THE FOAM ALIGNMENT SHIMS (ITEM 12) ARE TO BE INSERTED BETWEEN THE DMD EDGES AND THE OPTICAL INTERFACE AT THE APPROXIMATE LOCATIONS SHOWN. THE FUNCTION OF THE ELASTOMERIC WEDGES IS TO HOLD THE DMD AGAINST DATUMS 'B' AND 'C' AFTER IT HAS BEEN MANUALLY POSITIONED. THIS HOLDS THE DMD IN POSITION WHILE THE REMAINING ASSEMBLY IS COMPLETED
- [2] THE INSULATOR (ITEM 5) NEEDS TO BE OF SUFFICIENT THICKNESS TO ISOLATE THE PCB FROM THE METAL CLAMP (ITEM 6), TO KEEP IT FROM CAPACITIVELY COUPLING SIGNALS TOGETHER.
- [3] WHEN TIGHTENING SCREWS (ITEM 7) BE SURE CLAMPING FORCES DO NOT EXCEED THE MAXIMUM LOADS FOR THE THERMAL AND ELECTRICAL INTERFACE AREAS SPECIFIED IN THE DMD DATA SHEET. CARE SHOULD BE TAKEN AS THE SCREWS ARE TIGHTENED TO MAINTAIN A UNIFORM LOAD ACROSS THE AREAS.
- [4] CRITICAL GAP FOR COIL SPRING DESIGN TO CONTROL LOADS ON THE DMD ELECTRICAL INTERFACE AREA. THE SIZE OF THE GAP WILL VARY DEPENDING ON PART TOLERANCES AND SPRING PROPERTIES.
- [5] CRITICAL GAP FOR COIL SPRING DESIGN TO CONTROL LOADS ON THE DMD THERMAL INTERFACE AREA. THE SIZE OF THE GAP WILL VARY DEPENDING ON PART TOLERANCES AND SPRING PROPERTIES.



VIEW A - DMD ALIGNMENT TO OPTICAL CHASSIS



SECTION A-A



QTY	ITEM	PART NUMBER	DESCRIPTION	Notes
2	12	2512939	SHIM, FOAM ALIGNMENT (ELASTOMERIC WEDGE)	
4	11	LEE SPRING LC020CD 02M	COIL SPRING, THERMAL	
4	10	LEE SPRING LCM060B 02M	COIL SPRING, ELECTRICAL	
1	9	2519250	HEAT EXCHANGER CONCEPT      SERIES 323	
1	8	2519257	THERMAL PAD	
4	7	2519251	SCREW, SHOULDER	
1	6	2519247	CLAMP, SERIES 323	
1	5	2519249	INSULATOR, SERIES 323	
1	4	2519248	PCB, DMD ASSEMBLY, OUTLINE, SERIES 323	
1	3	2519244	INTERPOSER, 149 CONTACT, SERIES 323, HOLE DATUM	
1	2	DMD	DMD ASSEMBLY, SERIES 323	
1	1	2519246	INTERFACE, SERIES 323 MOUNTING CONCEPT 9245	

		<div>UNLESS OTHERWISE SPECIFIED</div> <ul style="list-style-type: none"><li>DIMENSIONS ARE IN MILLIMETERS</li><li>TOLERANCES: ANGLES ±1°<div>2 PLACE DECIMALS ±0.25</div><div>1 PLACE DECIMALS ±0.50</div></li><li>DIMENSIONAL LIMITS APPLY BEFORE PROCESSES</li><li>INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994</li><li>REMOVE ALL BURRS AND SHARP EDGES</li><li>PARENTHEITICAL INFO FOR REF ONLY</li></ul>	<div>DWN J. McKINLEY</div> <div>DATE</div>		<div><div><div></div><div>TEXAS INSTRUMENTS</div></div></div> <div>ASSEMBLY, SERIES 323 MOUNTING CONCEPT 9245</div>		
			Engr				
			CQE/QA				
			CM				
			Apprvd				
0314RD		SIZE B		DWG NO 2519245		REV A	
NEXT ASSY		USED ON		SCALE 1:2		SHEET 1 OF 2	
APPLICATION							

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SSZZ031 January 01, 2013



DWN  
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DATE \_\_\_\_\_

	SIZE B
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DRAWING NO

REV  
A

SCALE None

SHEET 2 OF 2